

3- Ω , High Bandwidth, Dual SPDT Analog Switch

DESCRIPTION

The DG2517, DG2518 are low-voltage dual single-pole/double-throw monolithic CMOS analog switches. Designed to operate from 1.8 V to 5.5 V power supply, the DG2517, DG2518 achieves a bandwidth of 242 MHz while providing low on-resistance ($3\ \Omega$), excellent on-resistance matching ($0.2\ \Omega$) and flatness ($1\ \Omega$) over the entire signal range.

The DG2517, DG2518 offers the advantage of high linearity that reduces signal distortion, making ideal for audio, video, and USB signal routing applications. Additionally, the DG2517, DG2518 are 1.6 V logic compatible within the full operation voltage range.

Built on Vishay Siliconix's proprietary sub-micron high-density process, the DG2517, DG2518 brings low power consumption at the same time as reduces PCB spacing with the MSOP10 and DFN10 packages.

As a committed partner to the community and the environment, Vishay Siliconix manufactures this product with the lead (Pb)-free device terminations. The DFN package has a nickel-palladium-gold device termination and is represented by the lead (Pb)-free "-E4" suffix. The MSOP package uses 100 % matte Tin device termination and is represented by the lead (Pb)- free "-E3" suffix. Both the matte Tin and nickel-palladium-gold device terminations meet all JEDEC standards for reflow and MSL ratings.

FEATURES

- 1.8 V to 5.5 V single supply operation
- Low R_{ON} : $3\ \Omega$ at 4.2 V
- 242 MHz, - 3 dB bandwidth
- Low off-isolation, - 51 dB at 10 MHz
- + 1.6 V logic compatible


RoHS
COMPLIANT

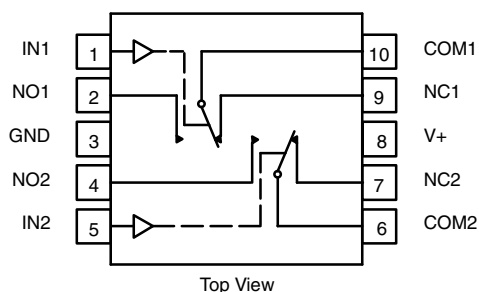
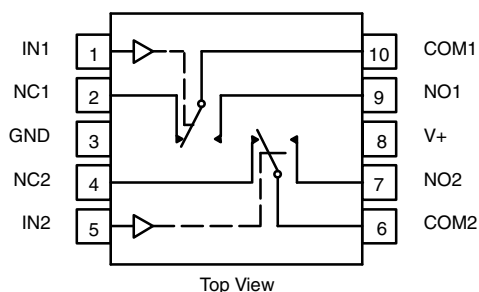
BENEFITS

- High linearity
- Low power consumption
- High bandwidth
- Full rail signal swing range

APPLICATIONS

- USB/UART signal switching
- Audio/video switching
- Cellular phone
- Media players
- Modems
- Hard drives
- PCMCIA

FUNCTIONAL BLOCK DIAGRAM AND PIN CONFIGURATION

DG2517

DG2518


TRUTH TABLE

Logic	NC1 and NC2	NO1 and NO2
0	ON	OFF
1	OFF	ON

ORDERING INFORMATION

Temp. Range	Package	Part Number
- 40 °C to 85 °C	MSOP-10	DG2517DQ-T1-E3
		DG2518DQ-T1-E3
	DFN-10	DG2517DN-T1-E4
		DG2518DN-T1-E4

ABSOLUTE MAXIMUM RATINGS

Parameter		Limit	Unit
Reference to GND			
V+		- 0.3 to + 6	V
IN, COM, NC, NO ^a		- 0.3 to (V+ + 0.3)	
Continuous Current (Any terminal)		± 50	mA
Peak Current (Pulsed at 1 ms, 10 % duty cycle)		± 200	
Storage Temperature (D Suffix)		- 65 to 150	°C
Power Dissipation (Packages) ^b	MSOP-10 ^c	320	mW
	DFN-10 ^d	1191	

Notes:

a. Signals on NC, NO, or COM or IN exceeding V+ will be clamped by internal diodes. Limit forward diode current to maximum current ratings.

b. All leads welded or soldered to PC board.

c. Derate 4.0 mW/°C above 70 °C.

d. Derate 14.9 mW/°C above 70 °C.

SPECIFICATIONS (V+ = 3 V)

Parameter	Symbol	Test Conditions Otherwise Unless Specified V+ = 3 V, ± 10 %, V _{IN} = 0.5 or 1.4 V ^e	Temp. ^a	Limits - 40 °C to 85 °C			Unit
				Min. ^b	Typ. ^c	Max. ^b	
Analog Switch							
Analog Signal Range ^d	V _{NO} , V _{NC} , V _{COM}		Full	0		V+	V
On-Resistance	R _{ON}	V+ = 2.7 V, V _{COM} = 1.5 V I _{NO/NC} = 10 mA	Room Full		3.2	4.5 5.0	Ω
R _{ON} Flatness	R _{ON} Flatness	V+ = 2.7 V, V _{COM} = 1.5, 2 V I _{NO/NC} = 10 mA	Room Full		1.0	1.4 16	
R _{ON} Match Between Channels	ΔR _{ON}	V+ = 2.7 V, V _{COM} = 1.5 V I _{NO/NC} = 10 mA	Room Full		0.1	0.3 0.4	
Switch Off Leakage Current ^f	I _{NO(off)} , I _{NC(off)}	V+ = 3.6 V, V _{NO} , V _{NC} = 0.3 V/ 3 V V _{COM} = 3 V/0.3 V	Room Full	- 1 - 10		1 10	nA
	I _{COM(off)}		Room Full	- 1 - 10		1 10	
Channel-On Leakage Current ^f	I _{COM(on)}	V+ = 3.6 V, V _{NO} , V _{NC} = V _{COM} = 0.3 V/3 V	Room Full	- 1 - 10		1 10	
Digital Control							
Input High Voltage ^d	V _{INH}		Full	1.4			V
Input Low Voltage	V _{INL}		Full			0.5	
Input Capacitance	C _{in}		Full		4		pF
Input Current	I _{INL} or I _{INH}		Full	1		1	μA
Dynamic Characteristics							
Turn-On Time	t _{ON}	V+ = 2.7 V, V _{NO} or V _{NC} = 1.5 V R _L = 300 Ω, C _L = 35 pF	Room Full		15	30 50	ns
Turn-Off Time	t _{OFF}		Room Full		10	25 35	
Break-Before-Make Time	t _d	V _{NO} or V _{NC} = 1.5 V, R _L = 300 Ω, C _L = 35 pF	Full	1			
Charge Injection ^d	Q _{INJ}	C _L = 1 nF, V _{GEN} = 1.5 V, R _{GEN} = 0 Ω	Room		1		pC
- 3 dB Bandwidth	BW	0 dBm, C _L = 5 pF, R _L = 50 Ω	Room		242		MHz
Off-Isolation ^d	OIRR	R _L = 50 Ω, C _L = 5 pF	f = 1 MHz	Room	- 71		dB
			f = 10 MHz	Room	- 51		
Crosstalk ^d	X _{TALK}	R _L = 50 Ω, C _L = 5 pF	f = 1 MHz	Room	- 73		
			f = 10 MHz	Room	- 55		
N _O , N _C Off Capacitance ^d	C _{NO(off)}	V _{IN} = 0 or V+, f = 1 MHz	Room		8		pF
	C _{NC(off)}		Room		8		
Channel-On Capacitance ^d	C _{NO(on)}		Room		35		
	C _{NC(on)}		Room		35		
Power Supply							
Power Supply Current	I+	V _{IN} = 0 or V+	Full		0.01	1.0	μA

Notes:

a. Room = 25 °C, Full = as determined by the operating suffix.

b. Typical values are for design aid only, not guaranteed nor subject to production testing.

c. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum, is used in this data sheet.

d. Guarantee by design, nor subjected to production test.

e. V_{IN} = input voltage to perform proper function.

f. Guaranteed by 5 V leakage testing, not production tested.



SPECIFICATIONS (V+ = 5 V)								
Parameter	Symbol	Test Conditions Otherwise Unless Specified V+ = 5 V, ± 10 %, VIN = 0.8 or 2.0 V ^e		Temp. ^a	Limits - 40 °C to 85 °C			Unit
					Min. ^b	Typ. ^c	Max. ^b	
Analog Switch								
Analog Signal Range ^d	VNO, VNC, VCOM			Full	0		V+	V
On-Resistance	RON	V+ = 4.2 V, VCOM = 3.5 V, INO/NC = 10 mA		Room Full		3	4.0 4.3	Ω
RON Flatness	RON Flatness	V+ = 4.2 V, VCOM = 1, 2, 3.5 V INO/NC = 10 mA		Room Full		1.1	1.4 1.6	
RON Match Between Channels	ΔRON	V+ = 4.2 V, VCOM = 3.5 V, INO/NC = 10 mA		Room Full		0.1	0.3 0.4	
Switch Off Leakage Current	INO(off), INC(off)	V+ = 5.5 V VNO, VNC = 1 V/4.5 V, VCOM = 4.5 V/1 V		Room Full	- 1 - 10		1 10	nA
	ICOM(off)			Room Full	- 1 - 10		1 10	
Channel-On Leakage Current	ICOM(on)	V+ = 5.5 V, VCOM = VNO, VNC = 1 V/4.5 V		Room Full	- 1 - 10		1 10	
Digital Control								
Input High Voltage ^d	VINH			Full	2.0			V
Input Low Voltage	VINL			Full			0.8	
Input Capacitance	Cin			Full		4		pF
Input Current	IINL or IINH	VIN = 0 V or V+		Full	1		1	μA
Dynamic Characteristics								
Turn-On Time	tON	V+ = 4.2 V, VNO or VNC = 3 V RL = 300 Ω, CL = 35 pF		Room Full		12	25 45	ns
Turn-Off Time	tOFF			Room Full		8	20 30	
Break-Before-Make Time	td	VNO or VNC = 3 V, RL = 300 Ω, CL = 35 pF		Full	1			
Charge Injection ^d	QINJ	CL = 1 nF, VGEN = 2.5 V, RGEN = 0 Ω		Room		2		pC
- 3 dB Bandwidth	BW	0 dBm, CL = 5 pF, RL = 50 Ω		Room		242		MHz
Off-Isolation ^d	OIRR	RL = 50 Ω, CL = 5 pF	f = 1 MHz	Room		- 71		dB
			f = 10 MHz	Room		- 51		
Crosstalk ^d	XTALK	RL = 50 Ω, CL = 5 pF	f = 1 MHz	Room		- 73		
			f = 10 MHz	Room		- 55		
Source-Off Capacitance ^d	CNO(off)	VIN = 0 or V+, f = 1 MHz		Room		8		pF
	CNC(off)			Room		8		
Channel-On Capacitance ^d	CNO(on)			Room		35		
	CNC(on)			Room		35		
Power Supply								
Power Supply Range	V+				1.8		5.5	V
Power Supply Current	I+	VIN = 0 or V+		Full		0.01	1.0	μA

Notes:

a. Room = 25 °C, Full = as determined by the operating suffix.

b. Typical values are for design aid only, not guaranteed nor subject to production testing.

c. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum, is used in this data sheet.

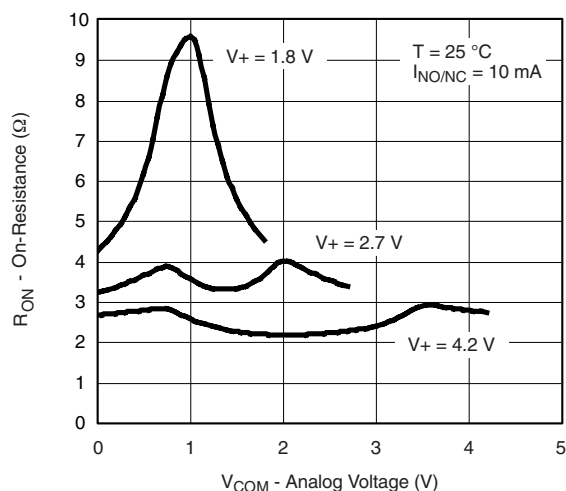
d. Guarantee by design, nor subjected to production test.

e. V_{IN} = input voltage to perform proper function.

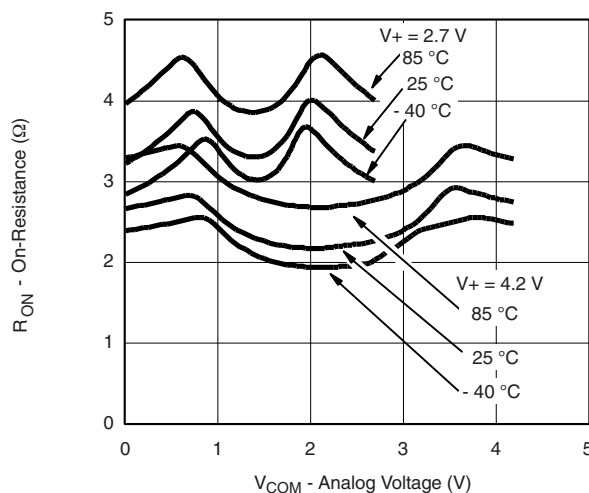
f. Guaranteed by 5 V leakage testing, not production tested.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

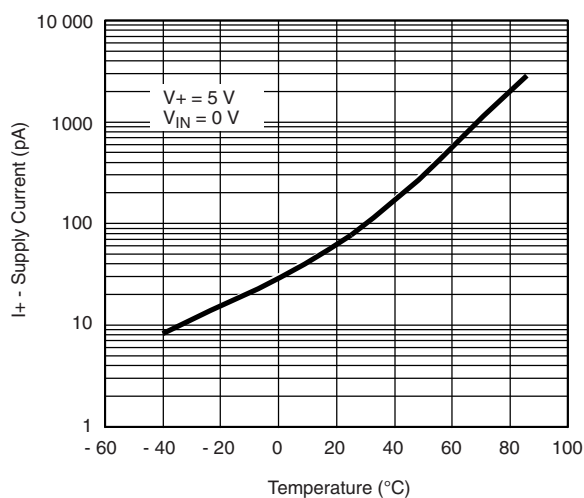
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



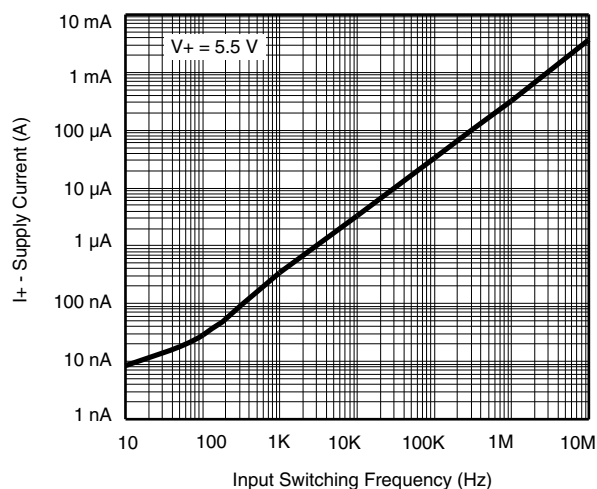
R_{ON} vs. V_{COM} and Supply Voltage



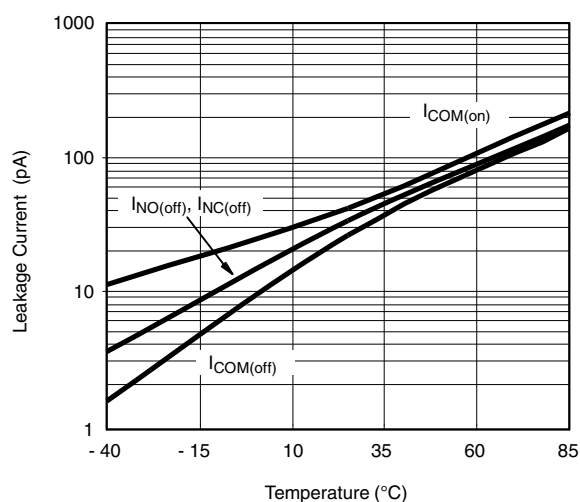
R_{ON} vs. Analog Voltage and Temperature



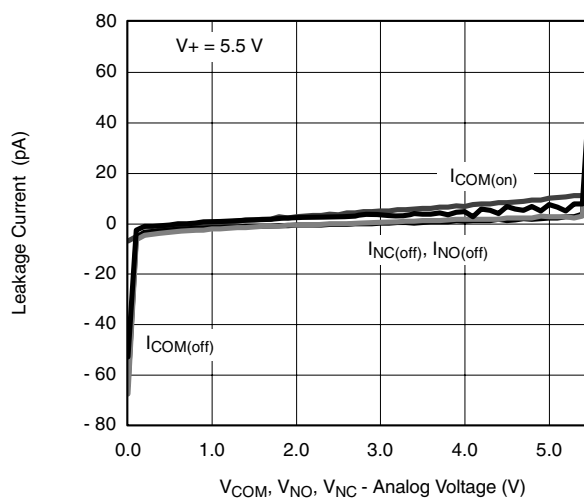
Supply Current vs. Temperature



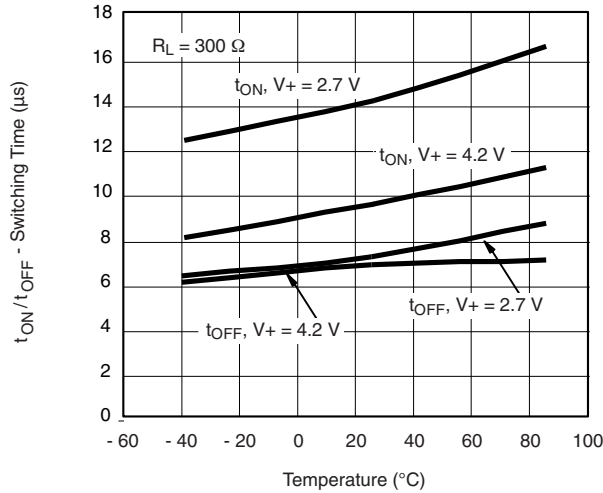
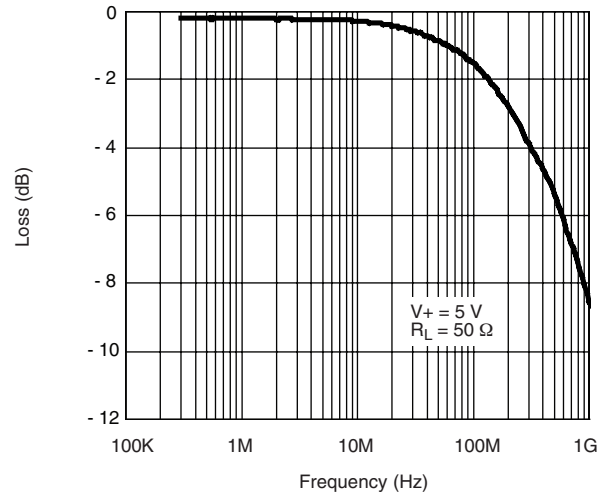
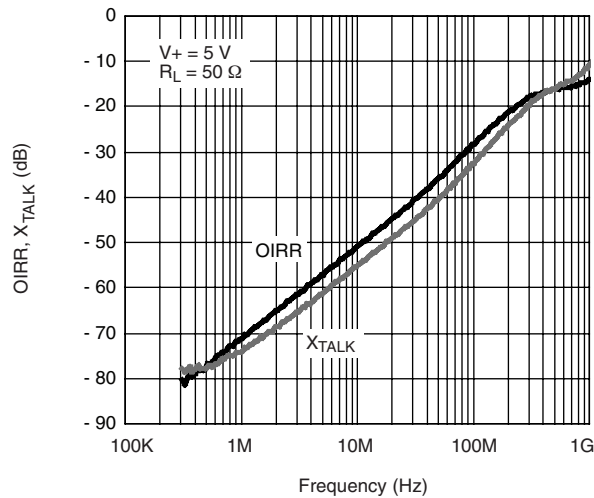
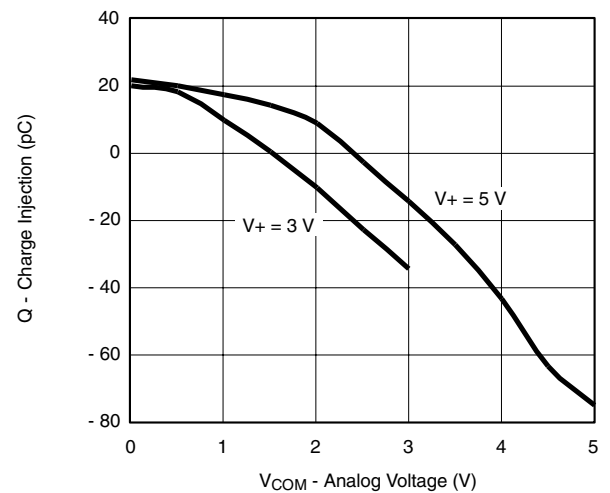
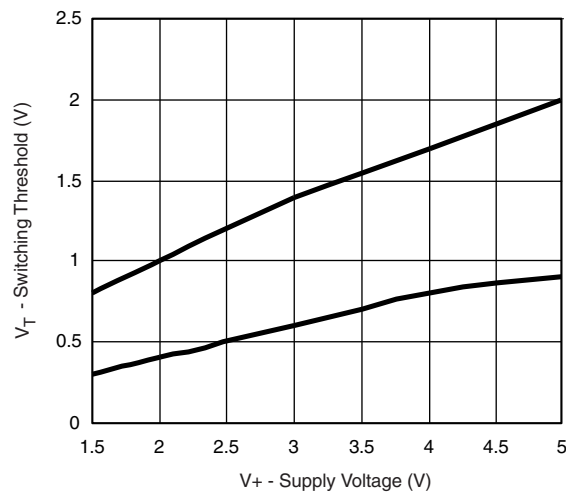
Supply Current vs. Input Switching Frequency



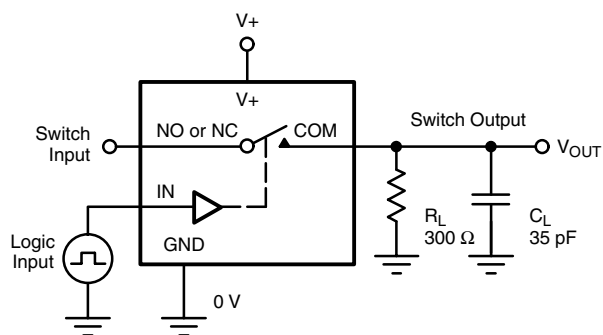
Leakage Current vs. Temperature



Leakage vs. Analog Voltage

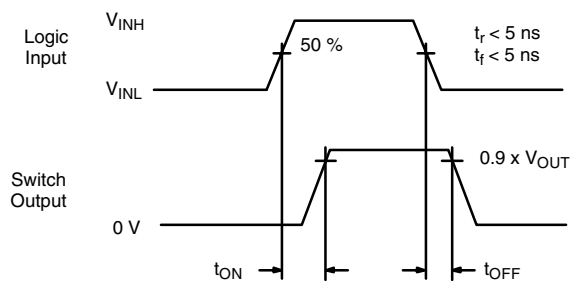
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Switching Time vs. Temperature

Insertion Loss vs. Frequency

Off-Isolation and Crosstalk vs. Frequency

Charge Injection vs. Analog Voltage

Switching Threshold vs. Supply Voltage

TEST CIRCUITS



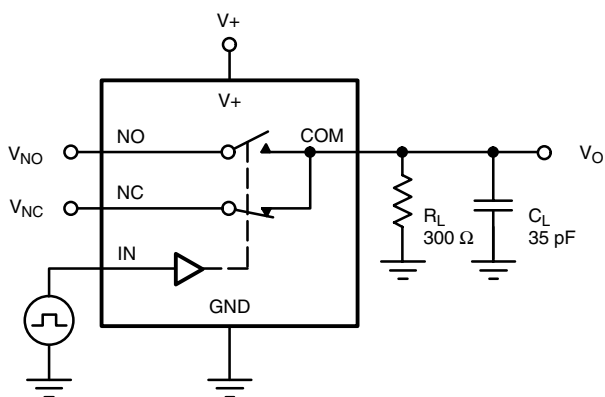
C_L (includes fixture and stray capacitance)

$$V_{OUT} = V_{COM} \left(\frac{R_L}{R_L + R_{ON}} \right)$$



Logic "1" = Switch On
Logic input waveforms inverted for switches that have the opposite logic sense.

Figure 1. Switching Time



C_L (includes fixture and stray capacitance)

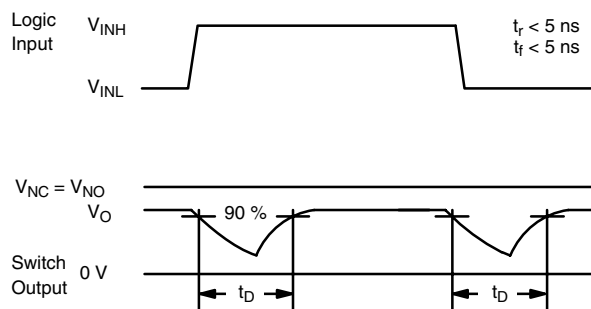
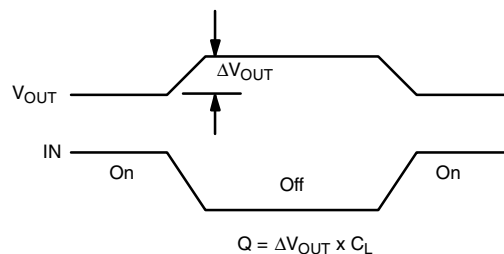
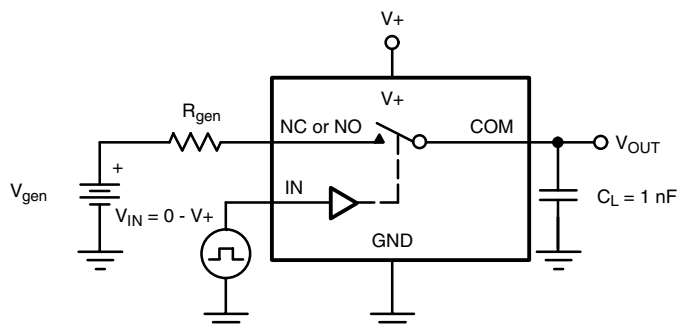
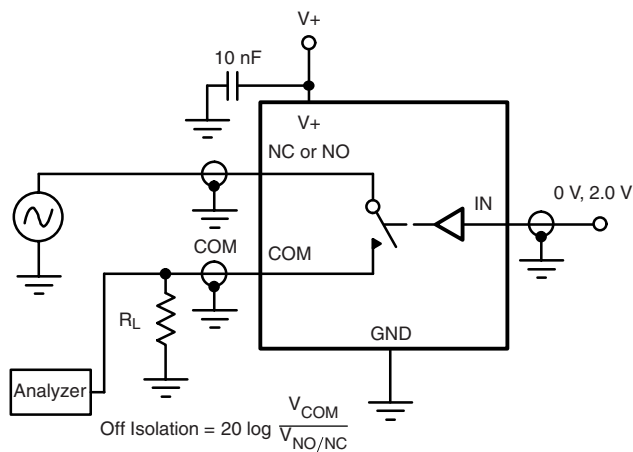
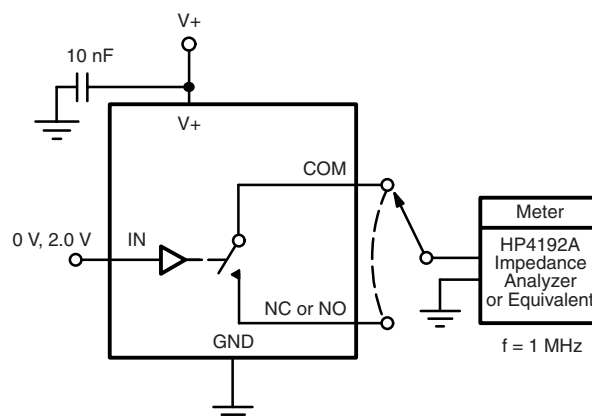


Figure 2. Break-Before-Make Interval



IN depends on switch configuration: input polarity determined by sense of switch.

Figure 3. Charge Injection

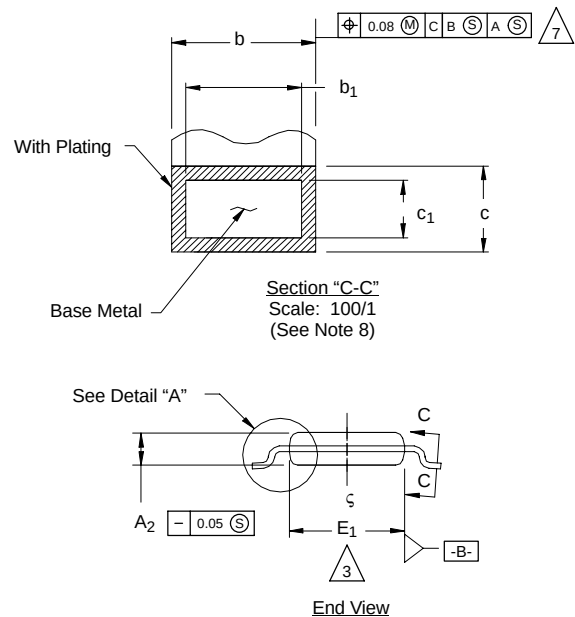
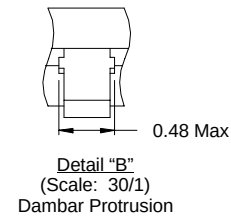
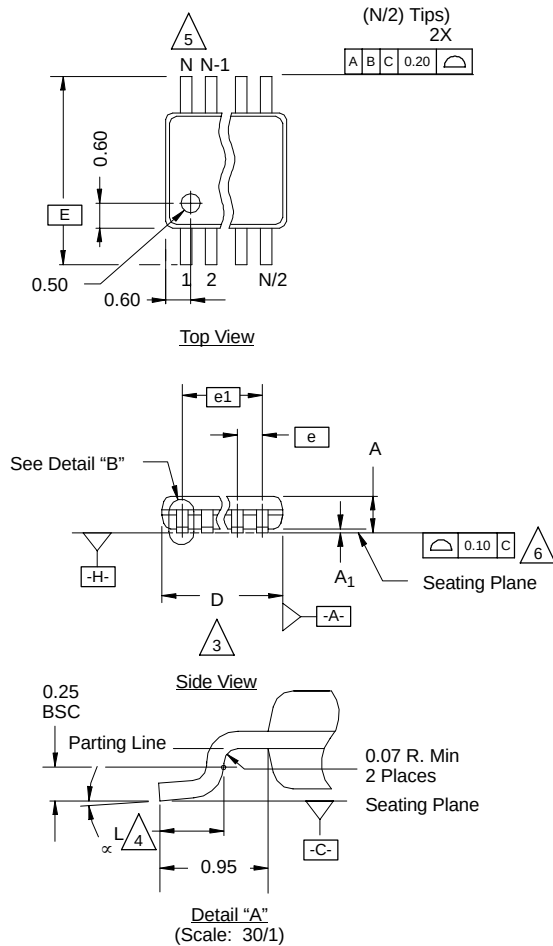
TEST CIRCUITS

Figure 4. Off-Isolation

Figure 5. Channel Off/On Capacitance

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <http://www.vishay.com/ppg?74333>.



MSOP: 10-LEADS

JEDEC Part Number: MO-187, (Variation AA and BA)



NOTES:

- Die thickness allowable is 0.203 ± 0.0127 .
- Dimensioning and tolerances per ANSI.Y14.5M-1994.
- Dimensions "D" and "E₁" do not include mold flash or protrusions, and are measured at Datum plane $\square H$, mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimension is the length of terminal for soldering to a substrate.
- Terminal positions are shown for reference only.
- Formed leads shall be planar with respect to one another within 0.10 mm at seating plane.
- The lead width dimension does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08 mm total in excess of the lead width dimension at maximum material condition. Dambar cannot be located on the lower radius or the lead foot. Minimum space between protrusions and an adjacent lead to be 0.14 mm. See detail "B" and Section "C-C".
- Section "C-C" to be determined at 0.10 mm to 0.25 mm from the lead tip.
- Controlling dimension: millimeters.
- This part is compliant with JEDEC registration MO-187, variation AA and BA.
- Datums $\square A$ and $\square B$ to be determined Datum plane $\square H$.
- Exposed pad area in bottom side is the same as the leadframe pad size.

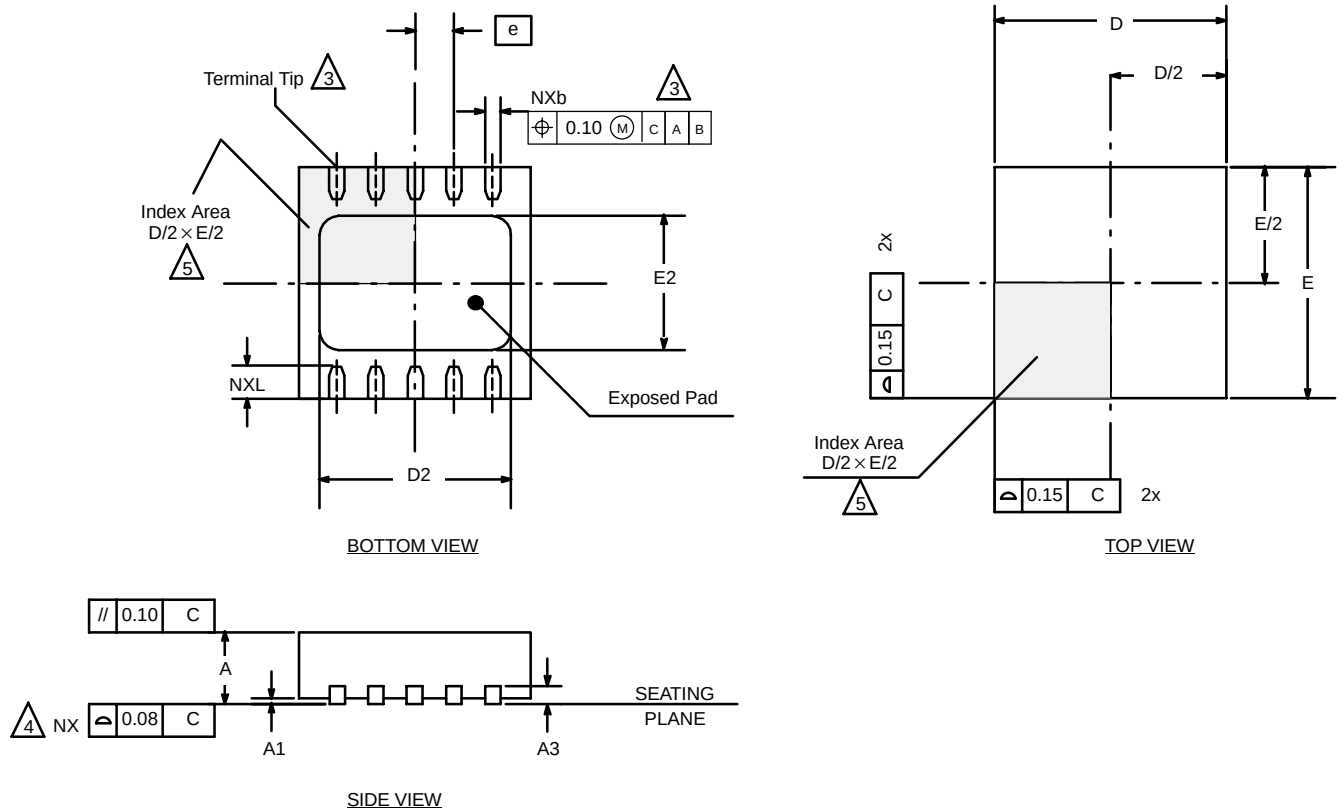
N = 10L

Dim	MILLIMETERS			Note
	Min	Nom	Max	
A	-	-	1.10	
A ₁	0.05	0.10	0.15	
A ₂	0.75	0.85	0.95	
b	0.17	-	0.27	8
b ₁	0.17	0.20	0.23	8
c	0.13	-	0.23	
c ₁	0.13	0.15	0.18	
D	3.00 BSC			3
E	4.90 BSC			
E ₁	2.90	3.00	3.10	3
e	0.50 BSC			
e ₁	2.00 BSC			
L	0.40	0.55	0.70	4
N	10			5
α	0°	4°	6°	

ECN: T-02080—Rev. C, 15-Jul-02
DWG: 5867



DFN-10 LEAD (3 X 3)



NOTES:

1. All dimensions are in millimeters and inches.

2. N is the total number of terminals.

3. Dimension b applies to metallized terminal and is measured between 0.15 and 0.30 mm from terminal tip.

4. Coplanarity applies to the exposed heat sink slug as well as the terminal.

5. The pin #1 identifier may be either a mold or marked feature, it must be located within the zone indicated.

Dim	MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max
A	0.80	0.90	1.00	0.031	0.035	0.039
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.20 BSC			0.008 BSC		
b	0.18	0.23	0.30	0.007	0.009	0.012
D	3.00 BSC			0.118 BSC		
D2	2.20	2.38	2.48	0.087	0.094	0.098
E	3.00 BSC			0.118 BSC		
E2	1.49	1.64	1.74	0.059	0.065	0.069
e	0.50 BSC			0.020 BSC		
L	0.30	0.40	0.50	0.012	0.016	0.020
*Use millimeters as the primary measurement.						
ECN: S-42134—Rev. A, 29-Nov-04						
DWG: 5943						



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Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

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